

Attorney Docket No.: 42P18071
Application No.: 10/773,099
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IN THE SPECIFICATION:

Please add the following new paragraph after paragraph [0008]:

[0008.1] Fig. 5 is a top view of a device that includes the heat pipe of Fig. 1.

Please replace paragraph [0021] with the following amended paragraph:

[0021] Vapor space 220 may be located between wick 120 and the top one of outer walls 110. Vapor-phase coolant 210 may be transported to the condenser portion of ~~heat~~ heat pipe 100 via vapor space 220 (and possibly also wick 120), where it cools, becomes liquid, and is transported back to boiling structure 130 by wick 120. In some implementations consistent with the principles of the invention, vapor space may have a height in a range from about 0.5 mm to about 2 mm, although other heights are possible.

Please replace paragraph [0025] with the following amended paragraph:

[0025] For example, although heat pipe 100 herein has been described by itself, other cooling techniques also may optionally be used. For example, as shown in Fig. 5, a cooling fan (or other forced-air cooling device) 510 may or may not be used in conjunction with heat pipe 100 within a mobile computer or other electronic device 500.